



CAC

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
MBHB No. 03-264-A

IN THE APPLICATION OF:)	
Hong Wan et al)	Examiner: Bot Ledynh
)	
Patent No. 7,095,226 B2)	Group Art Unit: 2862
)	
Serial No. 10/789,682)	Confirmation No.: 9346
)	
Filed: February 27, 2004)	
)	
Title Vertical Die Chip-On-Board)	

REQUEST FOR CERTIFICATE OF CORRECTION
PURSUANT TO 37 C.F.R. § 1.322

Attention: Certificate of Corrections Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Certificate
JUN 05 2007
of Correction

Dear Sir:

This is a request for issuance of the accompanying Certificate of Correction pursuant to 35 U.S.C. § 254 and 37 C.F.R. § 1.322(a). The Assignee of Record, **Honeywell International Inc.** seeks to correct mistakes of clerical, typographical nature and of minor character in the above-identified Patent. The corrections are as follows:

On the title page, at item [57], please delete: "Methods and apparatus for vertical chip-on-board sensor packages..." and replace with - - Methods and apparatus for vertical die chip-on-board sensor packages.... - -

In claim 11, Column 14, line 14, please delete "alone" and substitute - - along - -.

The Assignee respectfully submits that the requested corrections do not constitute new matter, nor do they require substantive examination of the file.

JUN - 5 2007

The Assignee respectfully submits that the above-mentioned error was a mistake of the Patent and Trademark Office and, thus, the Assignee believes that no fee is due. If the Examiner believes otherwise, the Assignee authorizes the Commissioner to deduct any fee from the Deposit Account No. 13-2490 pursuant to 37 C.F.R. §§ 1.20(a) and 1.323.

Enclosed is a completed Certificate of Correction for U.S. Patent No. 7,095,226 B2 issued August 22, 2006.

Consideration of this Request and issuance of the Certificate of Correction are respectfully requested.

Respectfully submitted,

Dated: May 22, 2007

By Jori R. Schiffman
Jori R. Schiffman
Registration No. 57,628

JUN - 5 2007

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
MBHB No. 03-264-A

IN THE APPLICATION OF:

Hong Wan et al

Patent No. 7,095,226 B2

Serial No. 10/789,682

Filed: February 27, 2004

Title Vertical Die Chip-On-Board



Examiner: Bot Ledynh

Group Art Unit: 2862

Confirmation No.: 9346

Attention: Certificate of Corrections Branch
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Sir:

TRANSMITTAL LETTER

In regard to the above identified application:

1. We are transmitting herewith the attached papers for the above identified patent application:

- a) Request for Certificate of Correction Pursuant to 37 C.F.R. § 1.322;
- b) Certificate of Correction for Patent No. 7,095,226 B2; and
- c) Return Postcard.

2. With respect to additional fees:

- a) No additional fee is required.
- b) Please charge any additional fees or credit overpayment to Deposit Account No. 13-2490. A duplicate copy of this sheet is enclosed.

CERTIFICATE OF MAILING UNDER 37 CFR § 1.8: The undersigned hereby certifies that this Transmittal Letter and the paper, as described in paragraph 1 hereinabove, are being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Attention: Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Respectfully submitted,

Date: May 22, 2007

By: Jori R. Schiffman
 Jori R. Schiffman
 Registration No. 57,628

JUN - 5 2007

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
MBHB No. 03-264-A

UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

Page 1 of 1

PATENT NO. : 7,095,226 B2

APPLICATION NO.: 10/789,682

ISSUE DATE: : August 22, 2006

INVENTOR(S) : Hong Wan et al

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the title page, at item [57], please delete: "Methods and apparatus for vertical chip-on-board sensor packages..." and replace with - - Methods and apparatus for vertical die chip-on-board sensor packages.... - -

In claim 11, Column 14, line 14, please delete "alone" and substitute - - along - -.

MAILING ADDRESS OF SENDER (Please do not use customer number below):

McDonnell, Boehnen, Hulbert, and Berghoff LLP
300 South Wacker Drive
Chicago, IL 60606

This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. **SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.**

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.

American LegalNet, Inc.
www.USCourtForms.com

JUN - 5 2007